

Abstract of the Disclosure:

In a chip type solid electrolytic capacitor including a capacitor element
5 and a packaging resin covering the capacitor element, the packaging resin has
a mount surface and a side surface adjacent to the mount surface. A terminal
is electrically connected to the capacitor element and coupled to the packaging
resin. The terminal extends along the mount surface and the side surface to
have an outer surface exposed from the packaging resin and to have an inner
10 surface opposite to the outer terminal surface. The inner surface has a
stepwise shape formed by forging.